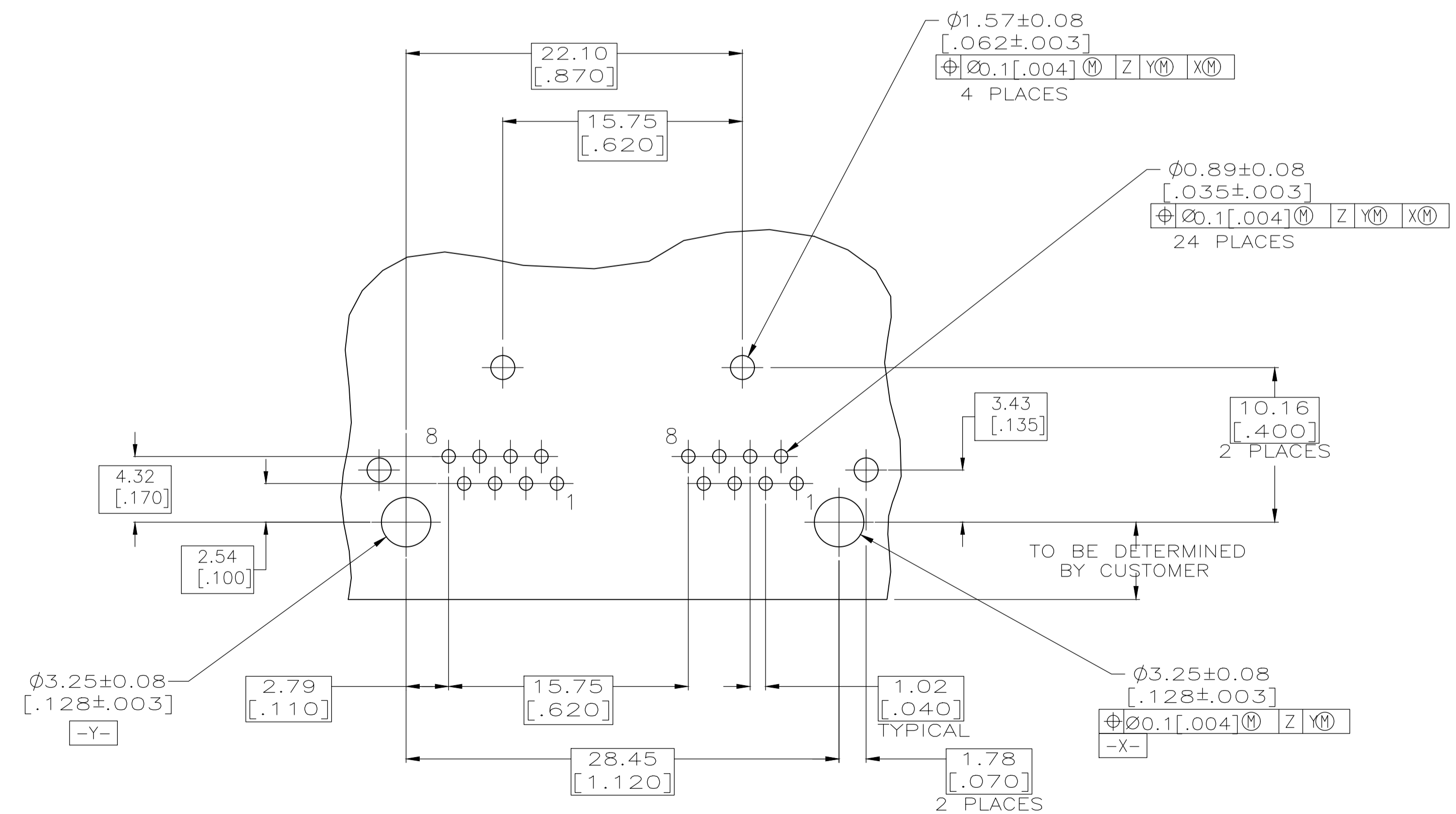
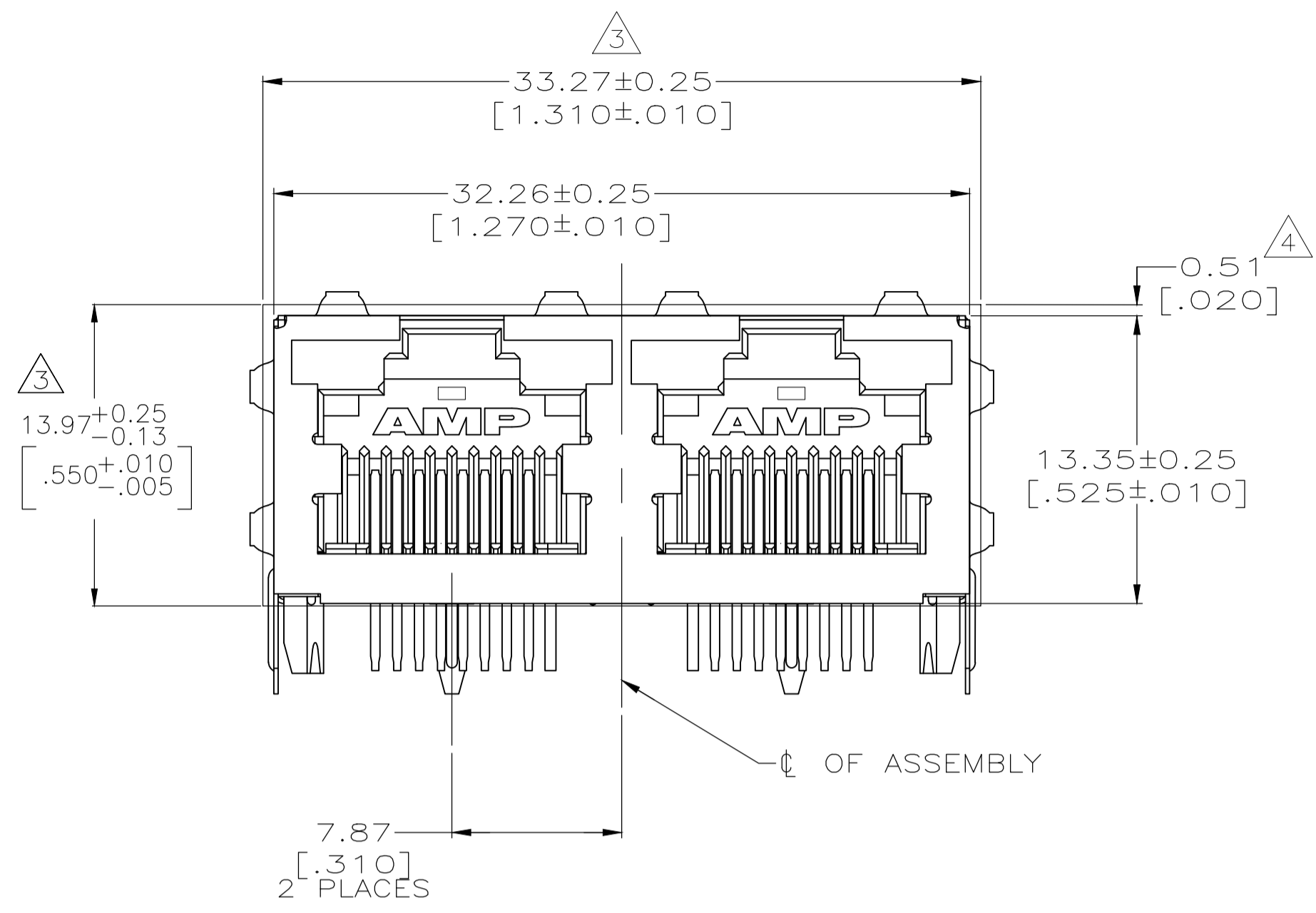
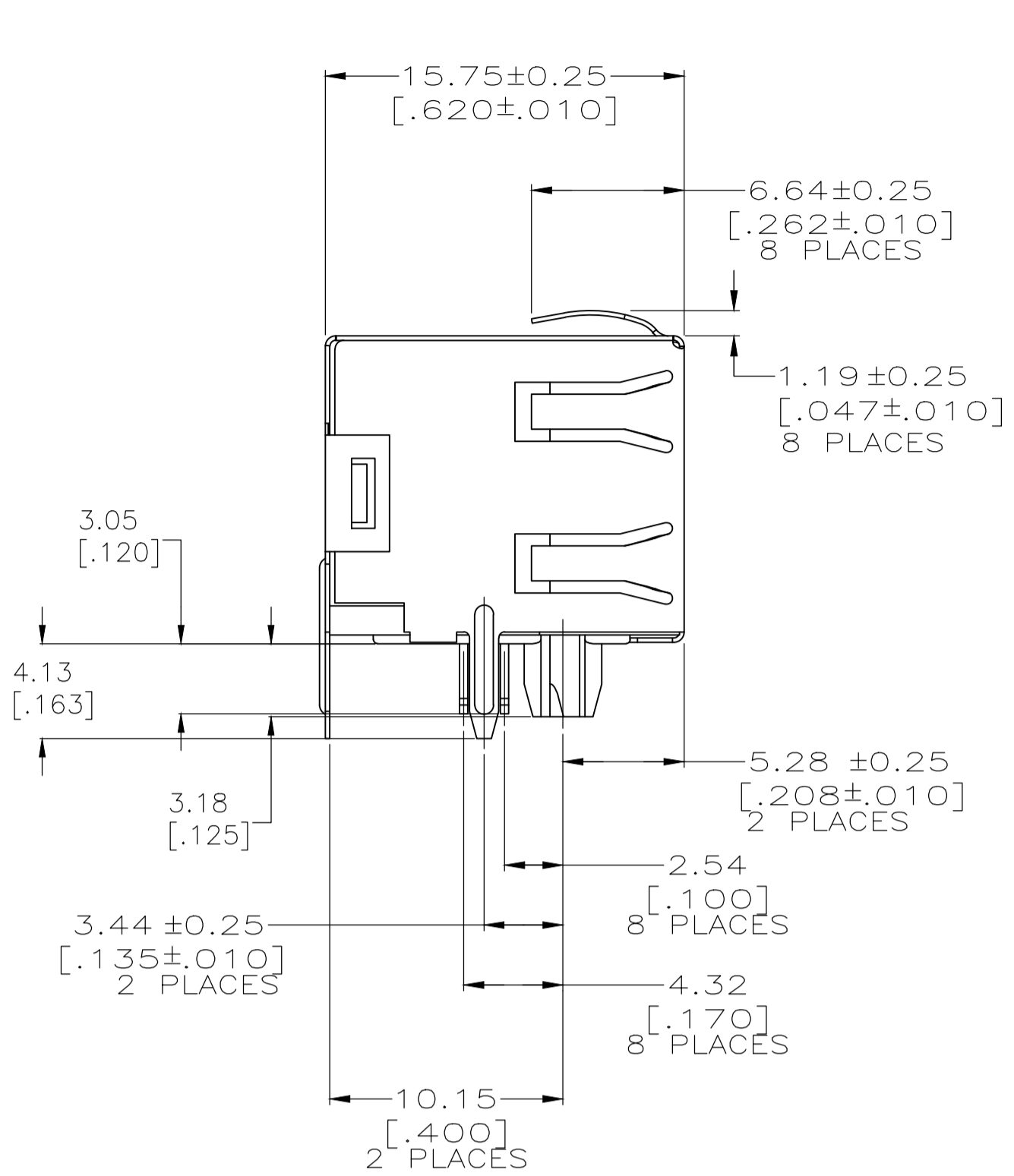


REVISIONS					
P	LTR	DESCRIPTION	DATE	DMN	APVD
B		ECC-18-014918	20AUG2019	RR	SH



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
(COMPONENT SIDE)

- MATERIAL: HOUSING - HIGH TEMPERATURE THERMOPLASTIC, COLOR: BLACK, UL94V-0

 TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK BRIGHT TIN LEAD IN SOLDER AREA. 1.27µm [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [.000050] MINIMUM THICK NICKEL.
 SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[.000050] MINIMUM SATIN NICKEL WITH 2.03µm[.000080] MINIMUM TIN POST DIPPED ON PCB GROUND TABS.
 - JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.
 △ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.

THIS DRAWING IS A CONTROLLED DOCUMENT.		DMN DL DRUMMOND 23SEP2003	TE Connectivity		
DIMENSIONS: mm [INCHES]		CHK EC LAURER 23SEP2003			
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD EC LAURER 23SEP2003	NAME		
0. PLC ± -			INVERTED MODULAR JACK ASSEMBLY, 1X2, SHIELDED, PANEL GROUND		
1. PLC ± -			PRODUCT SPEC		
2. PLC ± 0.25(.01)			108-1163-4		
3. PLC ± 0.13(.005)			APPLICATION SPEC		
4. PLC ± -			114-2154		
ANGLES ± -			SIZE CASE CODE DRAWING NO		
MATERIAL SEE NOTE 1		FINISH SEE NOTE 1	WEIGHT 0.000000	A1 00779 C=1368459	RESTRICTED TO
			CUSTOMER DRAWING	SCALE 4:1	SHEET 1 OF 1 REV B